HALOGEN

FREE

PFRR

# ESCC () 4001/023 Qualified R Failure Rate High Precision (10 ppm/°C, 0.05 %) Thin Film Chip Resistors



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**DESIGN SUPPORT TOOLS** 

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Vishay Sfernice Thin Film division holds ESCC QML qualification (ESCC technology flow qualification).

These HiRel components are ideal for low noise and precision applications, superior stability, low temperature coefficient of resistance, and low voltage coefficient, Vishay Sfernice's precision thin film wraparound resistors exceed requirements of MIL-PRF-55342G characteristics Y ( $\pm$  10 ppm/°C).

### **FEATURES**

- Load life stability at ± 70 °C for 2000 h: 0.25 % under Pn
- Temperature coefficient to: 10 ppm/°C
- Very low noise (< -35 dB) and voltage coefficient (< 0.01 ppm/V)</li>
- Resistance range: 100  $\Omega$  to 3.01 M $\Omega$  (depending on size)
- Tolerances down to 0.05 %
- SnPb terminations over nickel barrier
- ESCC 4001 (generic specification)
- ESCC 4001/023 (detail specification)
- ESCC qualified
- R failure rate (0.01 % per 1000 h)
- SMD wraparound chip resistor
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

STANDARD	STANDARD ELECTRICAL SPECIFICATIONS									
MODEL	SIZE	ESCC VARIANT NUMBER	RESISTANCE RANGE Ω	RATED POWER AT +70 °C (Pn) W	LIMITING ELEMENT VOLTAGE (UL) V	INSULATION VOLTAGE ( <i>U</i> i) V	TOLERANCE ± %	TEMPERATURE COEFFICIENT ± ppm/°C		
PFRR 0402 💽	0402	15	100 to 150K	0.05	40	50	0.05, 0.1	10, 25		
PFRR 0603 💽	0603	09	100 to 500K	0.1	50	100	0.05, 0.1	10, 25		
PFRR 0805 💽	0805	10	100 to 750K	0.125	100	200	0.05, 0.1	10, 25		
PFRR 1206 💽	1206	11	100 to 3.5M	0.25	150	300	0.05, 0.1	10, 25		
PFRR 2010 💽	2010	12	100 to 6M	0.50	200	300	0.05, 0.1	10, 25		

CLIMATIC SPECIFICATIONS					
Operating temperature range	-55 °C; +155 °C				
Soldering temperature (T <sub>sol</sub> )	260 °C, immersion 10 s				

MECHANICAL	MECHANICAL SPECIFICATIONS					
Substrate material	Alumina					
Technology	Thin Film					
Film	Nickel Chromium with mineral passivation					
Protection	Epoxy and Silicon					
Terminations	<b>B type:</b> SnPb over nickel barrier for solder reflow					

QUALIFIED OHMIC RANGE: MAX. VALUE							
PFRR0402	PFRR0603	PFRR0805	PFRR1206	PFRR2010			
100 kΩ	261 kΩ	301 kΩ	1 MΩ	3.01 MΩ			

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### **DIMENSIONS** in millimeters

VARIANT	STYLE	1	4	I	3	(	C	[	)	I	
NUMBER	STILE	Min.	Max.								
09	0603	1.39	2.16	0.62	1.01	0.25	1.02	0.17	0.51	0.25	0.51
10	0805	1.78	2.55	1.14	1.53	0.25	1.02	0.17	0.51	0.25	0.51
11	1206	2.87	3.64	1.47	1.86	0.25	1.02	0.17	0.51	0.25	0.51
12	2010	4.95	5.72	2.41	2.8	0.25	1.02	0.35	0.85	0.35	0.85
15	0402	0.87	1.64	0.47	0.86	0.25	1.02	0.09	0.38	0.12	0.38

LAND PATTERN DIMENSIONS in millimeters						
G <sub>min.</sub>						
CHIP SIZE	Z <sub>max.</sub>	G <sub>min.</sub>	X <sub>max.</sub>			
0402	1.55	0.15	0.73			
0603	2.37	0.35	0.98			
0705/0805	2.76	0.74	1.40			
0705/0805 1206	2.76 3.91	0.74 1.85	1.40 1.73			

#### Note

Suggested land pattern: According to IPC-7351

### TRACEABILITY DEFINITIONS

The two major traceability elements are defined as:

- The primary process lot number named Front End lot (FE lot). One "FE lot" is composed of several wafers issued from the same thin film deposition sequence.
- The date code named Batch Number(BN). The "BN" is defined after completion of the end of production testing sequence. The lot homogeneity is given by the "FE lot" and not by the "BN".

According to the applied rules validated by the ESCC through the product qualification, the following situations are agreed:

- Parts coming from different "FE lost" might have the same "BN".
- A maximum of two different "BN" might be applied to the same "FE lot" to enable the use of overruns from a previous PO.
- Unless requested / approved by the customer the "BN" will be 2 years old maximum.

### SPECIFIC TRACEABILITY REQUIREMENTS

The following specific requirements have to be treated as:

- A customer who requires "Lot Homogeneity" has to mention it on the PO as "SINGLE PRODUCTION LOT".
- A customer who requires "Lot Homogeneity" in addition to a "Single Batch Number" has to mention it on the PO as "SINGLE PRODUCTION LOT AND OPTION R0101".

### END OF PRODUCTION TESTING

Mandatory testing performed at the end of the production process:

• 100 % overload: Voltage  $\sqrt{(6.25 P_n \times R_n)}$  or 2  $U_L$  whichever is less - duration 2 s

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### **GLOBAL PART NUMBER INFORMATION**

New Global Part	New Global Part Numbering: PFRR0603Y1003BBT (preferred part number format)							
P F	R R 0	6 0 3 Y	1 0 0	3 B	ВТ			
TYPE PFRR0402 PFRR0603 PFRR0805 PFRR1206 PFRR2010	TCR Y = ± 10 ppm/°C E = ± 25 ppm/°C	$\begin{tabular}{ c c c c } \hline CHMIC & VALUE & \\ \hline The first three digits are significant figures and the last digit specifies the number of zeros to follow. & \\ Example: & $3901 = 3900 \ \Omega$ & $1004 = 1 \ M\Omega$ & \\ \hline \end{tabular}$	TOLERANCE W = ± 0.05 % B = ± 0.10 %	TERMINATION B: SnPb over nickel barrier	PACKAGING For more information see Codification of Packaging table			

CODIFICATION OF PACK	CODIFICATION OF PACKAGING						
CODE 18	PACKAGING						
WAFFLE PACK							
W	100 min., 1 mult						
WA	100 min., 100 mult (available only in size 1206)						
PLASTIC TAPE (in standard for a	Il sizes except 0402)						
Т	100 min., 1 mult						
ТА	100 min., 100 mult						
ТВ	250 min., 250 mult						
тс	500 min., 500 mult						
TD	1000 min., 1000 mult						
TE	2500min., 2500 mult						
TF	Full tape (quantity depending on size of chips)						
PAPER TAPE (in standard for 040	2, option for other sizes)						
PT	100 min., 1 mult						
PA	100 min., 100 mult						
РВ	250 min., 250 mult						
PC	500 min., 500 mult						
PD	1000 min., 1000 mult						
PE	2500min., 2500 mult						
PF	Full tape (quantity depending on size of chips)						

GLOBAL P	ART NUM	BER INFORM	IATION				
ESCC Code							
4 0 0 1 0 2 3 0 9 R 1 0 0 3 B 1							
ESCC SPEC	VARIANT	FAILURE RATE	OHMIC VALUE	TOLERANCE	TCR		
4001023	<b>0402</b> = 15	R	The first three digits are significant figures and the	<b>W</b> = ± 0.05 %	<b>1</b> = ± 10 ppm/°C		
	<b>0603</b> = 09		last digit specifies the number of zeros to follow.	<b>B</b> = ± 0.10 %	<b>2</b> = ± 25 ppm/°C		
	<b>0805</b> = 10		Example:	·			
	<b>1206</b> = 11		<b>3901</b> = 3900 Ω				
	<b>2010</b> = 12		<b>1004</b> = 1 ΜΩ				

# PFRR





Vishay Sfernice thin film is the first passive manufacturer to hold the ESCC Technology Flow Qualification, official certificate is available on ESCIES web site https://escies.org/ReadArticle?docId=727).

This qualification open the door to a new concept at ESA: The Failure Rate option (similar to the one offered in the MIL system), for instance R failure rate: 0.01 % per 1000 h.

New specifications describing this new concept have been released by the ESA:

2544001: Requirements for the Technology Flow Qualification of Film Resistors

https://escies.org/escc/specifications/2544001.pdf

26000: Failure Rate Level Sampling Plans and Procedures <a href="https://escies.org/escc/specifications/26000.pdf">https://escies.org/escc/specifications/26000.pdf</a>

21300: Terms, Definitions, Abbreviations, Symbols and Units <u>https://escies.org/escc/specifications/21300.pdf</u>

21700: General Requirements for the Marking of the ESCC Components

https://escies.org/escc/specifications/21700.pdf

4001: Generic Specification Resistors Fixed Film

https://escies.org/escc/specifications/4001.pdf 4001023: Resistors, Fixed, Chip, Thin Film, Type PHR and PFRR

https://escies.org/escc/specifications/4001023.pdf

Parts are delivered with space C.O.C.

Parts undergo 100 % overload at end of production process.

VARIANT	MODEL	CASE SIZE	TERMINATION
15	PFRR	0402	B (tin/lead)
09	PFRR	0603	B (tin/lead)
10	PFRR	0805	B (tin/lead)
11	PFRR	1206	B (tin/lead)
12	PFRR	1210	B (tin/lead)

#### ESCC/PFRR CODIFICATION CORRESPONDANCE TABLES

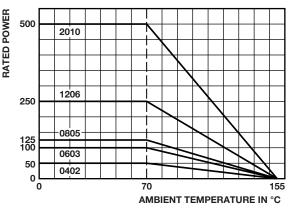
TEMPERATURE COEFFICIENT	ESCC CODE	PFRR CODE
10 ppm/°C (- 55 °C; + 155 °C)	1	Y
25 ppm/°C (- 55 °C; + 155 °C)	2	E

TOLERANCE	MODEL	CASE SIZE
0.1 %	В	В
0.05 %	W	W

#### PACKAGING Two types of packaging are available: waffle-pack and tape and reel. NUMBER OF PIECES PER PACKAGE WAFFLE TAPE AND REEL TAPE SIZE WIDTH PACK MIN MAX. 2" × 2" 0402 340 5000 0603 100 0805 100 8 mm 4000 1206 140

2000

#### **POWER DERATING CURVE**



### **EXTENDED FEATURES**

You may consult Vishay Sfernice for chip sizes, ohmic values and tolerances outside of the qualified range.

2010

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PERFORMANCE				
TEST	CONDITIONS	REQUIREMENTS		TYPICAL
		ESA/SCC 4001/023	MIL-PRF-55342G	TTPICAL
Short time overload	$U = \sqrt{(6.25 \text{ Pr x Rn})}$ $U_{\text{max.}} < 2 \text{ UL} - 2 \text{ s}$	± 0.05 % + (0.05 Ω x 100/Rn)	0.10 %	± 0.01 %
Rapid temperature change	- 55 °C/+ 155 °C 5 cycles CEI 66-2-14 Test Na	± 0.05 % + (0.05 Ω x 100/Rn)	0.1 % (for 100 cycles)	± 0.01 % ± 0.015 % (for 500 cycles)
Soldering (thermal shock)	260 °C/10 s CEI 68-2-20 A Test T6 (met. 1A)	± 0.05 % + (0.05 Ω x 100/Rn)	-	± 0.005 %
Terminal strength: Adhesion bend strength of end plated facing	CEI 115-1 Clause 4.32 CEI 115-1 Clause 4.33	± 0.05 % + (0.05 Ω x 100/Rn)	-	± 0.01 %
Climatic sequence	CEI 67-2-1/CEI 68-2-2 CEI 67-2-13/CEI 68-2-30	± 0.10 % + (0.05 Ω x 100/Rn)	-	$\pm$ 0.02 % Insulation resistance > 1 G $\Omega$
Load life	2000 h Pr at + 70 °C 90'/30' cycle 8000 h	± 0.25 % + (0.05 Ω x 100/Rn) 1 % + (0.05 Ω x 100/Rn)	0.5 %	$\pm$ 0.05 % (8000 h) Insulation resistance > 1 $G\Omega$
High temperature exposure	2000 h Pr at + 155 °C CEI 68-2-20A Test B	± 0.15 % + (0.05 Ω x 100/Rn)	± 0.10 % (duration 1000 h)	$\pm$ 0.05 % Insulation resistance > 1 G $\Omega$



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